

C1808C223K1RACTU

Aliases (C1808C223K1RAC7800) SMD Comm X7R, Ceramic, 0.022 uF, 10%, 100 VDC, X7R, SMD, MLCC, Temperature Stable, Class II, 1808, 2.9 mm



General Information	
Series	SMD Comm X7R
Style	SMD Chip
Description	SMD, MLCC, Temperature Stable, Class II
Features	Temperature Stable, Class II
RoHS	Yes
Termination	Tin
Marking	No
AEC-Q200	No
Typical Component Weight	41 mg
Shelf Life	78 Weeks
MSL	1

Dimensions	
Chip Size	1808
L	4.7mm +/-0.5mm
W	2mm +/-0.2mm
Т	0.9mm +/-0.10mm
S	2.9mm MIN
В	0.6mm +/-0.35mm

Т	0.9mm +/-0.10mm	Voltage DC
S	2.9mm MIN	Dielectric Withstanding Voltage
В	0.6mm +/-0.35mm	Temperature Range
		Temp. Coefficient
Packaging Specifications		Capacitance Change with
Packaging	T&R, 180mm, Plastic Tape	Reference to +25°C and 0 VDC Applied (TCC)
Packaging Quantity	2500	Dissipation Factor

Specifications	
Capacitance	0.022 uF
Measurement Condition	1 kHz 1.0Vrms
Tolerance	10%
Voltage DC	100 VDC
Dielectric Withstanding Voltage	250 VDC
Temperature Range	-55/+125°C
Temp. Coefficient	X7R
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	15%, 1kHz 1.0Vrms
Dissipation Factor	2.5% 1 kHz 1.0Vrms
Aging Rate	3% Loss/Decade Hour: Referee Time is 1000 Hours
Insulation Resistance	45.4545 GOhms

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